DATA SHEET

For a complete data sheet, please also download:

- The IC04 LOCMOS HE4000B Logic Family Specifications HEF, HEC
- The IC04 LOCMOS HE4000B Logic Package Outlines/Information HEF, HEC

HEF4011B
gates
Quadruple 2-input NAND gate

Product specification
File under Integrated Circuits, IC04

January 1995

Philips Semiconductors

PHILIPS

Quadruple 2-input NAND gate

HEF4011B gates

DESCRIPTION

The HEF4011B provides the positive quadruple 2-input NAND function. The outputs are fully buffered for highest noise immunity and pattern insensitivity of output impedance.

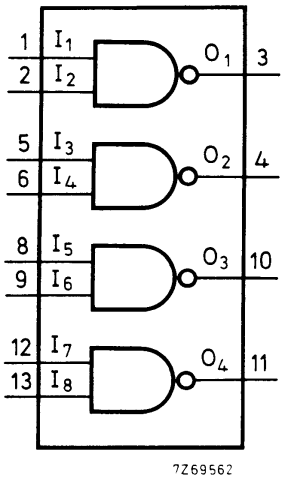


Fig.1 Functional diagram.

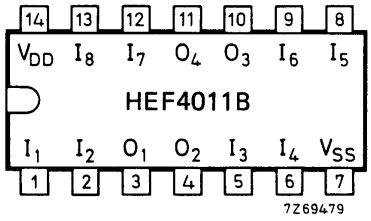


Fig.2 Pinning diagram.

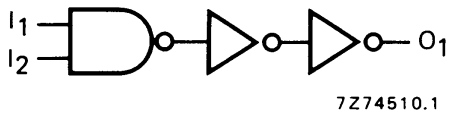


Fig.3 Logic diagram (one gate).

HEF4011BP(N): 14-lead DIL; plastic (SOT27-1)

HEF4011BD(F): 14-lead DIL; ceramic (cerdip) (SOT73)

HEF4011BT(D): 14-lead SO; plastic (SOT108-1)

( ): Package Designator North America

FAMILY DATA, I_{DD} LIMITS category GATES

See Family Specifications

AC CHARACTERISTICS

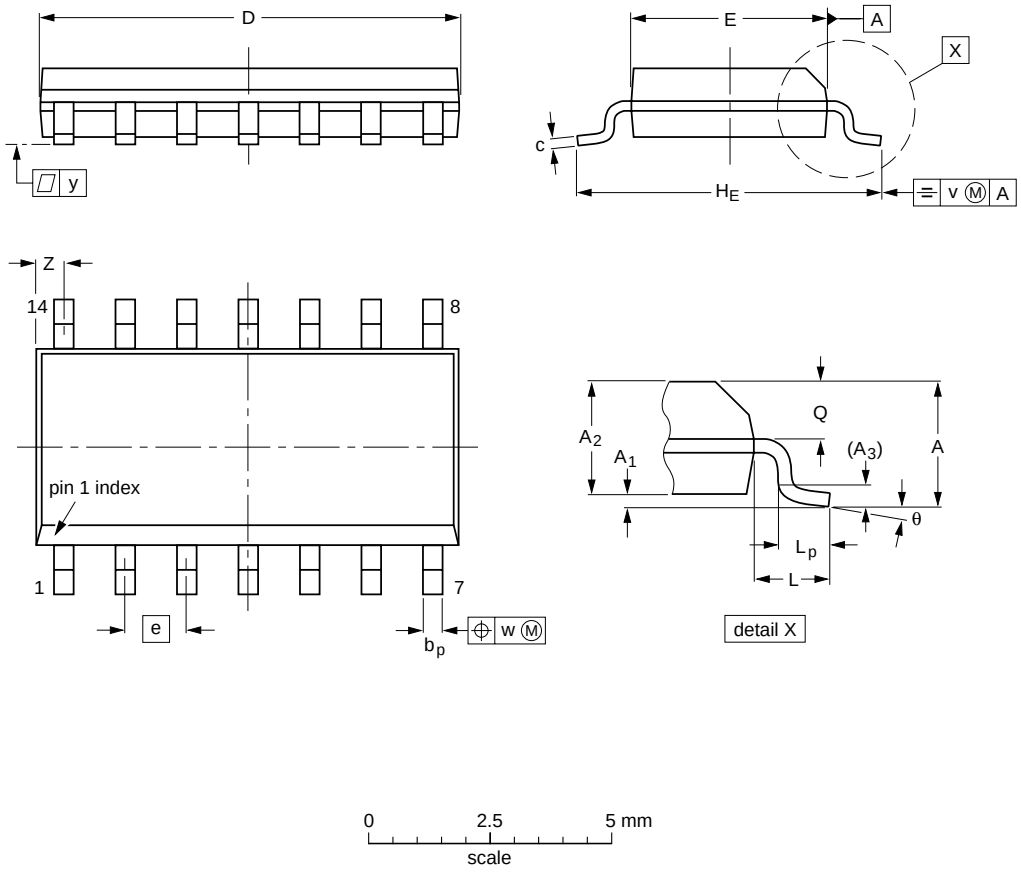
V_{SS} = 0 V; T_{amb} = 25 °C; C_L = 50 pF; input transition times ≤ 20 ns

	V_{DD} V	SYMBOL	TYP	MAX		TYPICAL EXTRAPOLATION FORMULA
Propagation delays	5		55	110	ns	28 ns + (0,55 ns/pF) C_L
$I_n \rightarrow O_n$	10	t_{PHL}; t_{PLH}	25	45	ns	14 ns + (0,23 ns/pF) C_L
	15		20	35	ns	12 ns + (0,16 ns/pF) C_L
Output transition times	5		60	120	ns	10 ns + (1,0 ns/pF) C_L
HIGH to LOW	10	t_{THL}	30	60	ns	9 ns + (0,42 ns/pF) C_L
	15		20	40	ns	6 ns + (0,28 ns/pF) C_L
	5		60	120	ns	10 ns + (1,0 ns/pF) C_L
LOW to HIGH	10	t_{TLH}	30	60	ns	9 ns + (0,42 ns/pF) C_L
	15		20	40	ns	6 ns + (0,28 ns/pF) C_L

	V_{DD} V	TYPICAL FORMULA FOR P (μW)	
Dynamic power	5	$1300\ f_i + \sum (f_o C_L) \times V_{DD}^2$	where
dissipation per	10	$6000\ f_i + \sum (f_o C_L) \times V_{DD}^2$	f_i = input freq. (MHz)
package (P)	15	$20\ 100\ f_i + \sum (f_o C_L) \times V_{DD}^2$	f_o = output freq. (MHz)
			C_L = load capacitance (pF)
			$\sum (f_o C_L)$ = sum of outputs
			V_{DD} = supply voltage (V)

SO

SO14: plastic small outline package; 14 leads; body width 3.9 mm SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8^o 0^o
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.35 0.34	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

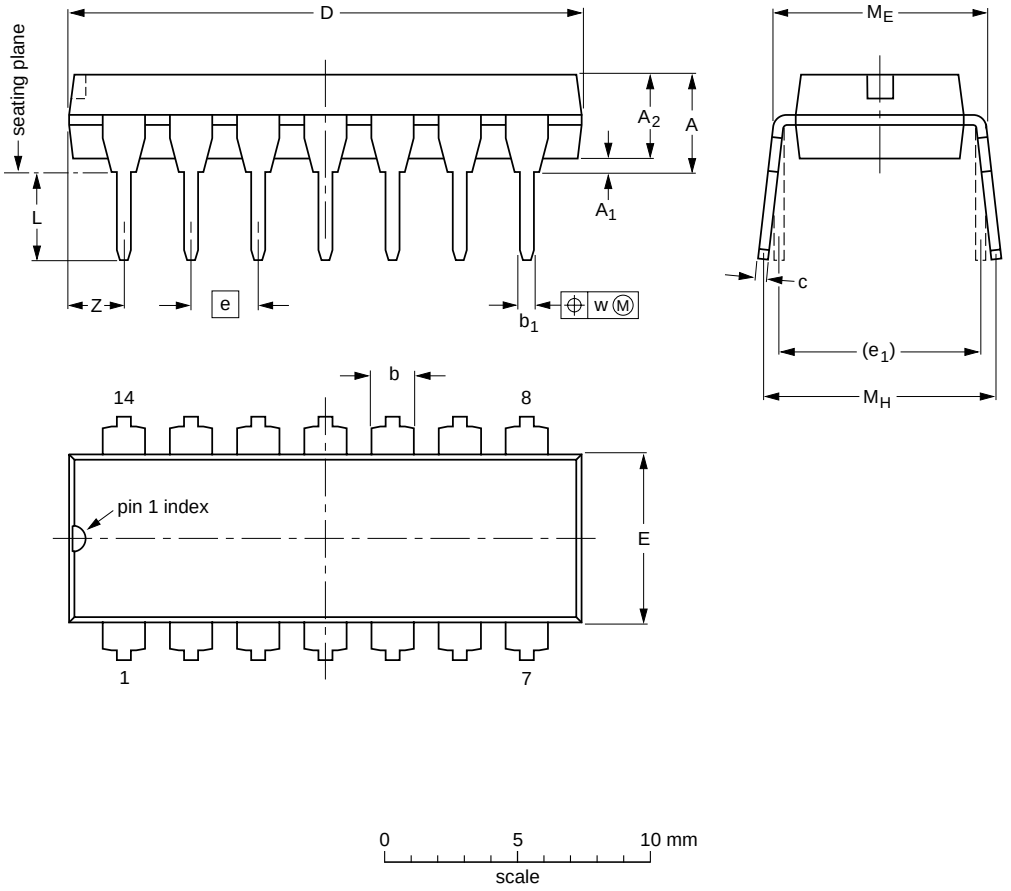
Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT108-1	076E06S	MS-012AB				~~95-01-23~~ 97-05-22

DIP

DIP14: plastic dual in-line package; 14 leads (300 mil) SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1 min.	A_2 max.	b	b_1	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT27-1	050G04	MO-001AA				~~92-11-17~~ 95-03-11